

Intel® 4th Gen. Haswell® Core™ i7-4700EQ MIL-STD Fanless Rugged System

Extended
Temperature
+85°C
-40°C

CPU Full Speed



POWER AUTOMATION COMPUTER

- Design for reliability under demanding MIL-STD-810G Thermal conditions
- 4th Generation Intel® Core™
- i7-4700EQ Haswell Processor
- XR-DIMM up to 8 GB RAM
- Onboard uSSD SATAIII 64 GB
- 2 x mPCIe expansion slot (One Co-Layout with mSATA)
- 2 x PCIe Intel® Gigabit Ethernet
- 9V to 36V DC-in with power delay on/off

Specifications

SYSTEM

CPU	Intel® Core™ i7 Haswell , BGA type Core i7-4700EQ (4C x 2.4/1.7 GHz), 6M Cache (47W)
Memory type	1 x DDR3 1600 XR-DIMM up to 8 GB with ECC
Chipset	Intel® QM87 PCH
Expansion Slot	2 x mPCIe (1 x colay with mSATA)
Storage Device	Onboard uSSD SATAIII up to 64 GB

REAR I/O

Power	1 x Terminal Block
Ethernet	2 x RJ45
COM	1 x RS232/422/485 with 5V/12V selectable
USB	2 x USB 3.0
DVI-I	1 (Default CLOSED)
DisplayPort	2
Audio	1 x MIC, 1 x Line out

FRONT I/O

Button	Power Button w/cover
Power LED	1 x Green LED
HDD LED	1 x Red LED
LAN LED	2 x Red LED, 2 Green LED
USB Port	2 x USB3.0 standard-A connectors

MECHANICAL & ENVIRONMENT

Power Requirements	9V to 36V DC-in, AT/ATX mode sup-ports with power delay on/off
Dimension(W xH x D)	308 x 149 x 59 mm
Operating Temp	-40 to 70°C (ambient with air flow)
Storage Temp.	-40 to 85°C
Relative Humidity	5% to 95%, non-condensing

SERIAL INTERFACE

& SIGNALS

Serial Standards	1x RS-232/422/485 port, Jumper-selectable (DB9 male)
RS-232	TxD, RxD, DTR, DSR, RTS, CTS, DCD, GND
RS-422	TxD+, TxD-, RxD+, RxD-, GND
RS-485-4w	TxD+, TxD-, RxD+, RxD-, GND
RS-485-2w	Data+, Data-, GND

ENVIRONMENTAL

MIL-STD-810G Test	Method 507.5, Procedure II (Temperature & Humidity) Method 516.6 Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6 Shock-Procedure I Operating (Mechanical Shock) Method 514.6 Vibration Category 24/Non-Operating (Category 20 & 24, Vibration) Method 514.6 Vibration Category 20/Operating (Category 20 & 24, Vibration) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock)
EMC	CE and FCC compliance
Green Product	RoHS, WEEE compliance

Ordering Information

SR10-SCH

MIL-STD Fanless Rugged System with Intel® Core™ i7 Haswell, 4 x USB3.0, 2 x DisplayPort, Extended range of Temperature -40°C to 70°C

SR10-SCH

Dimension

PERFECTRON

